

Abstract of the Disclosure

1 An electronic parts mount apparatus for taking out
2 semiconductor chips from a semiconductor wafer held on a
3 wafer hold section by a transfer head comprising a
4 plurality of suction nozzles and transporting and mounting
5 the semiconductor chips to and on a board has a parts
6 recognition camera disposed in a manner that it can advance
7 to and retreat from the wafer hold section for picking up
8 an image of the semiconductor wafer. A parts mounting
9 step for mounting a plurality of semiconductor chips on the
10 board by the transfer head and an image picking up step for
11 picking up a plurality of semiconductor chips to be next
12 taken out by the parts recognition camera are performed
13 concurrently. Thereby, the number of electronic parts per
14 mount turn can be increased, the tact time can be
15 shortened, and the electronic parts can be efficiently
16 taken out and mounted on the board.